

# SOT472-1

plastic ball grid array package; 156 balls; body 15 x 15 x 1.15 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	BGA156
<b>Package type industry code</b>	BGA156
<b>Package style descriptive code</b>	BGA (ball grid array)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>IEC package outline code</b>	144E
<b>JEDEC package outline code</b>	MS-034
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	22-1-2003

Table 1. Package summary

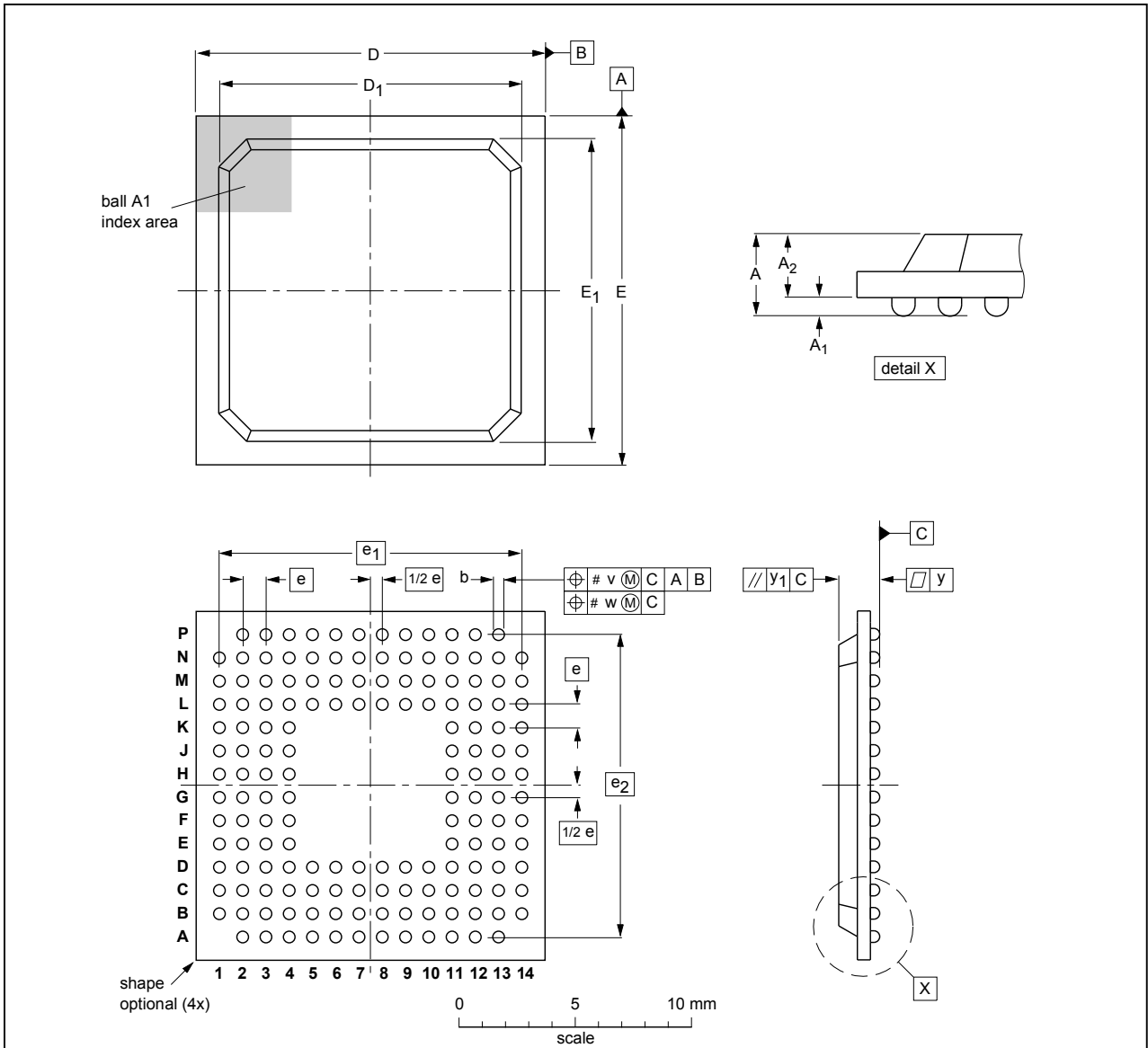
Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	14.8	-	15	15.2	mm
E	package width	14.8	-	15	15.2	mm
A	seated height	[tbd]	-	1.75	1.75	mm
A <sub>2</sub>	package height	1.05	-	1.15	1.25	mm
n <sub>2</sub>	actual quantity of termination	-	-	156	-	



2. Package outline

BGA156: plastic ball grid array package; 156 balls; body 15 x 15 x 1.15 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	b	D	D <sub>1</sub>	E	E <sub>1</sub>	e	e <sub>1</sub>	e <sub>2</sub>	v	w	y	y <sub>1</sub>
mm	1.75	0.5 0.3	1.25 1.05	0.6 0.4	15.2 14.8	13.7 13.0	15.2 14.8	13.7 13.0	1	13	13	0.3	0.1	0.15	0.35

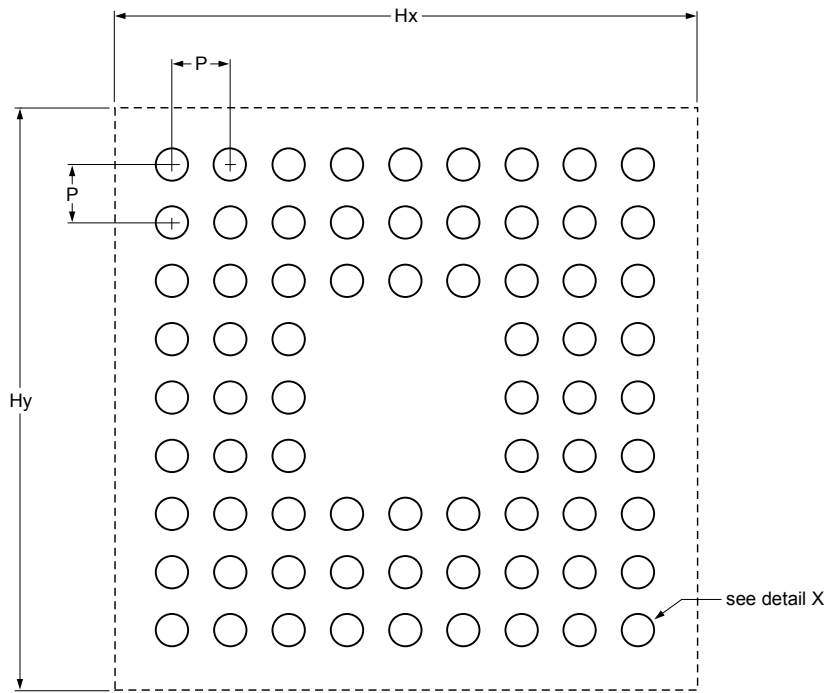
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT472-1	144E	MS-034	---			00-03-04- 03-01-22

Fig. 1. Package outline BGA156 (SOT472-1)




### 3. Soldering

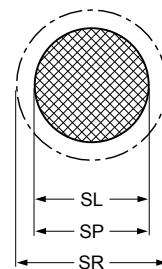
Footprint information for reflow soldering of BGA156 package

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Generic footprint pattern  
Refer to the package outline drawing for actual layout

-  solder land
-  solder paste deposit
-  solder land plus solder paste
- occupied area
- solder resist



detail X

DIMENSIONS in mm

P	SL	SP	SR	Hx	Hy
1.00	0.450	0.450	0.600	15.575	15.575

sot472-1\_fr

Fig. 2. Reflow soldering footprint for BGA156 (SOT472-1)

## 4. Legal information

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